

1SS400T1

Preferred Device

High-Speed Switching Diode

Features

- High-Speed Switching Applications
- Lead Finish: 100% Matte Sn (Tin)
- Qualified Maximum Reflow Temperature: 260°C
- Extremely Small SOD-523 Package
- This is a Pb-Free Device

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Reverse Voltage	V _R	100	V
Forward Current	I _F	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T _A = 25°C Derate above 25°C	P _D	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA}	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 @ Minimum Pad.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Max	Unit
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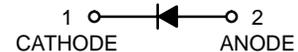
OFF CHARACTERISTICS

Reverse Voltage Leakage Current (V _R = 80 Vdc)	I _R	-	0.1	μAdc
Diode Capacitance (V _R = 0 V, f = 1.0 MHz)	C _D	-	3.0	pF
Forward Voltage (I _F = 100 mAdc)	V _F	-	1.2	Vdc
Reverse Recovery Time (I _F = I _R = 10 mAdc)	t _{rr}	-	4.0	ns



ON Semiconductor®

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SOD-523
CASE 502
PLASTIC

MARKING DIAGRAM



A = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
1SS400T1	SOD-523*	3000/Tape & Reel
1SS400T1G	SOD-523*	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*This package is inherently Pb-Free.

Preferred devices are recommended choices for future use and best overall value.

1SS400T1

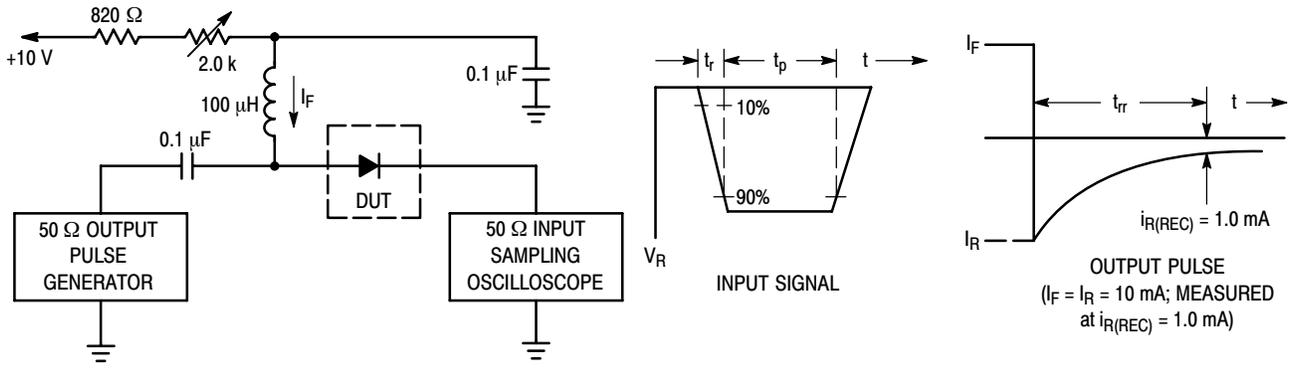


Figure 1. Recovery Time Equivalent Test Circuit

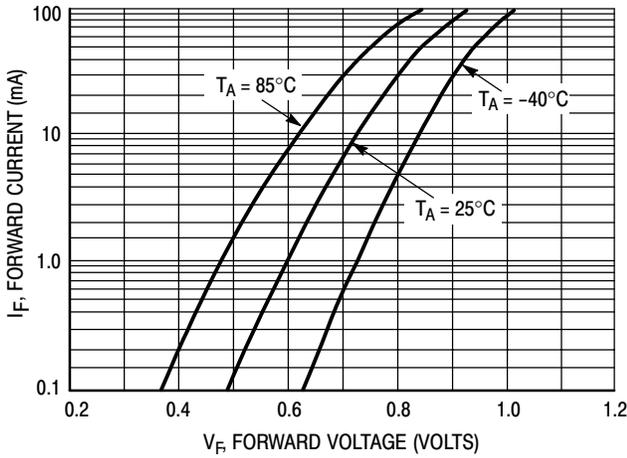


Figure 2. Forward Voltage

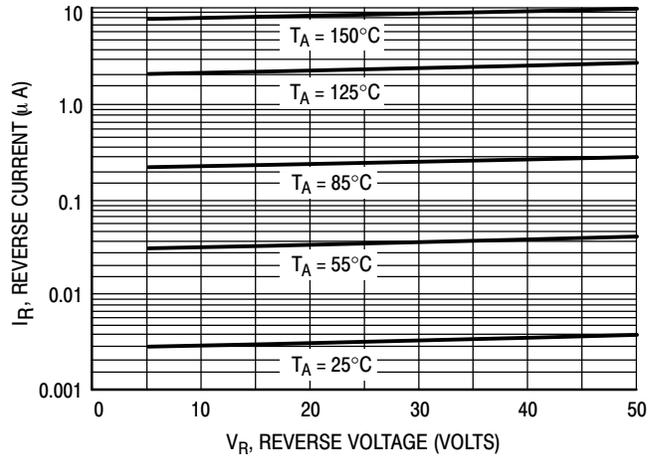


Figure 3. Leakage Current

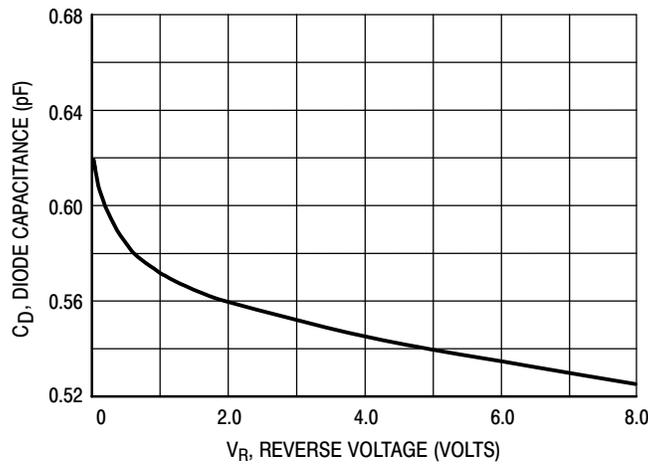
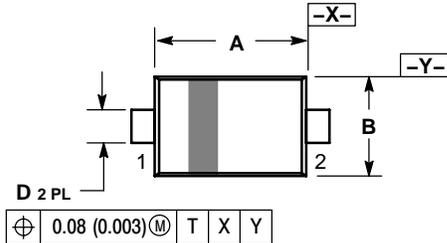


Figure 4. Capacitance

1SS400T1

PACKAGE DIMENSIONS

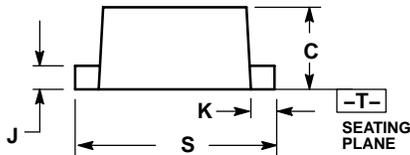
SOD-523
CASE 502-01
ISSUE B



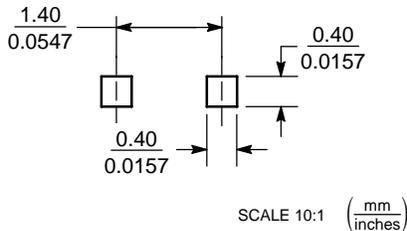
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.10	1.20	1.30	0.043	0.047	0.051
B	0.70	0.80	0.90	0.028	0.032	0.035
C	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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